

ESDALC6V1-1M2

Single line low capacitance Transil™ for ESD protection

Features

- Single line low capacitance Transil diode
- Unidirectional ESD protection
- ESD protection > 30 kV (IEC 61000-4-2 contact discharge)
- Breakdown voltage V_{BR} = 6.1 V min.
- Low diode capacitance (22 pF @ 0 V)
- Low leakage current (< 100 nA @ 3 V)
- Very small PCB area (0.6 mm²)
- RoHS compliant

Benefits

- High ESD protection level
- High integration
- Suitable for high density boards

Complies with the following standards:

- IEC 61000-4-2 level 4
 - 15 kV (air discharge)
 - 8 kV (contact discharge)
- MIL STD 883G Method 3015-7: class 3B
 - HBM (Human body model)

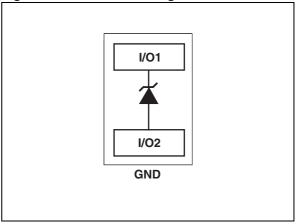
Applications

Where transient overvoltage protection in ESD sensitive equipment is required, such as:

- Computers
- Printers
- Communication systems
- Cellular phone handsets and accessories
- Video equipment



Figure 1. Functional diagram



Description

The ESDALC6V1-1M2 is a unidirectional single line TVS diode designed to protect the data lines or other I/O ports against ESD transients.

The device is ideal for applications where both reduced line capacitance and board space saving are required.

TM: Transil is a trademark of STMicroelectronics

Characteristics ESDALC6V1-1M2

1 Characteristics

Table 1. Absolute maximum ratings ($T_{amb} = 25 \, ^{\circ}C$)

Symbol	Parameter	Value	Unit
V_{PP}	ESD discharge - IEC 61000-4-2 contact discharge	±30	kV
P _{PP}	Peak pulse power dissipation (8/20 μs) ⁽¹⁾	50	W
I _{PP}	Repetitive peak pulse current (8/20 µs)	6	Α
T _j	Junction temperature	125	°C
T _{stg}	Storage temperature	- 55 to +150	°C
T _L	Maximum lead temperature for soldering during	260	°C
T _{OP}	Operating temperature range	- 40 to + 125	°C

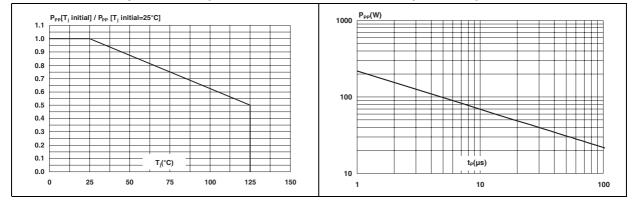
^{1.} For a surge greater than the maximum values, the diode will fail in short-circuit

Table 2. Electrical characteristics

Symbol	Parameter								' † /		
V_{RM}	Stand-of voltage						1 _F -				
V _{BR}	Break	Breakdown voltage									
V _{CL}	Clamp	Clamping voltage						V _{CL} V _{BR} V _{RM}			
I _{RM}	Leaka	Leakage current @ V _{RM}						I _{RM}			
I _{PP}	Peak p	Peak pulse current						Slope= 1/R _d			
αΤ	Voltage temperature coefficient										
V _F	Forwa	orward voltage drop									
Order code		V _{BR} @ I _R			I _{RM} @ V _{RM}		R_D	V _F @ 10 mA	αΤ	C @ 0 V	
Order CC	Jue	Vmin	Vmax	mA	nA max	٧	Ω typ	V max	10-4/°C max	pF typ	
ESDALC6V	1-1M2	6.1	7.2	1	100	3	0.5	1	4.5	22	

Figure 2. Peak power dissipation versus initial junction temperature

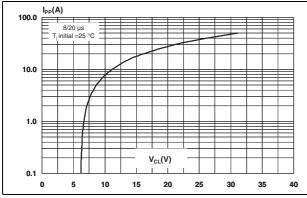
Figure 3. Peak pulse power versus exponential pulse duration



ESDALC6V1-1M2 Characteristics

Figure 4. Clamping voltage versus peak pulse current, rectangular waveform

Figure 5. Forward voltage drop versus peak forward current (typical values)



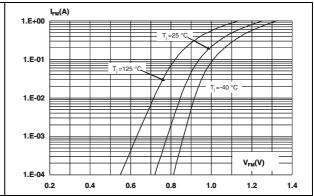
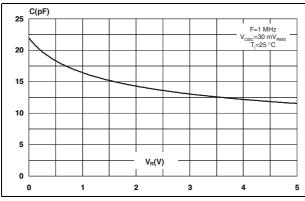


Figure 6. Capacitance versus reverse applied Figure 7. voltage (typical values)

Relative variation of the leakage current versus junction temperature (typical values)



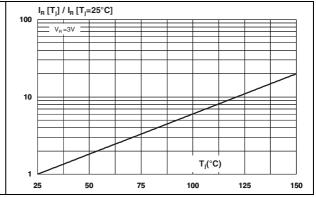
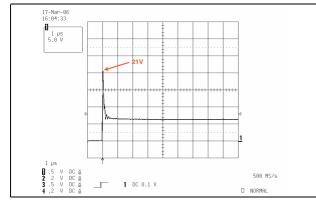
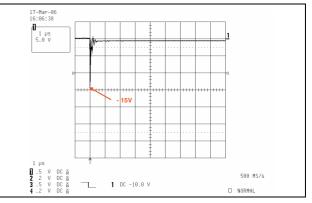


Figure 8. ESD response to IEC 61000-4-2 (+15 kV air discharge) on each channel

Figure 9. ESD response to IEC 61000-4-2 (-15 kV air discharge) on each channel





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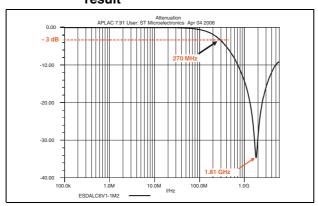
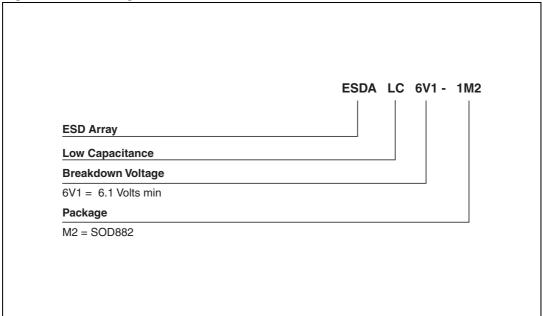


Figure 10. S21 attenuation measurement result

2 Ordering information scheme

Figure 11. Ordering information scheme



ESDALC6V1-1M2 Package information

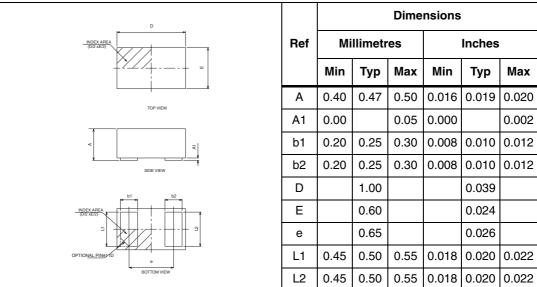
3 Package information

Epoxy meets UL94, V0

In order to meet environmental requirements, ST (also) offers these devices in ECOPACK® packages. ECOPACK® packages are Lead-free. The category of second level Interconnect is marked on the inner box label, in compliance with JEDEC Standard JESD97. The maximum ratings related to soldering conditions are also marked on the inner box label.

ECOPACK is an ST trademark. ECOPACK specifications are available at: www.st.com.

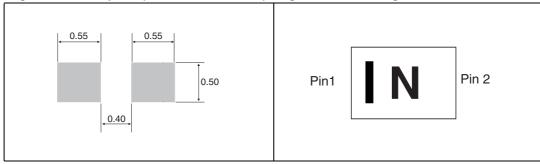
Table 3. SOD882 dimensions



Note:

Product marking may be rotated by 90° for assembly plant differentiation. In no case should this product marking be used to orient the component for its placement on a PCB. Only pin 1 mark is to be used for this purpose.

Figure 12. Footprint (dimensions in mm) Figure 13. Marking



Package information ESDALC6V1-1M2

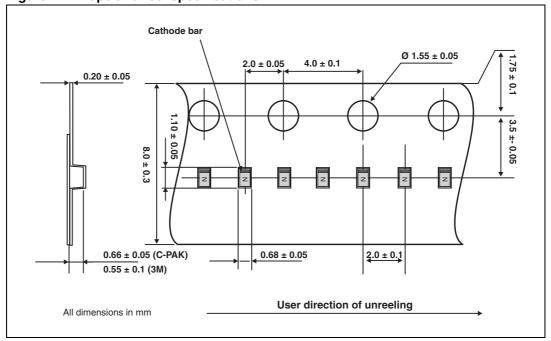


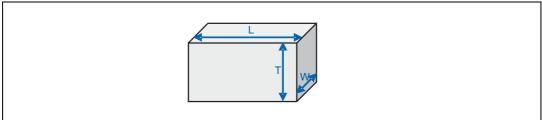
Figure 14. Tape and reel specifications

4 Recommendation on PCB assembly

4.1 Stencil opening design

- 1. General recommendation on stencil opening design
 - a) Stencil opening dimensions: L (Length), W (Width), T (Thickness).

Figure 15. Stencil opening dimensions



b) General design rule

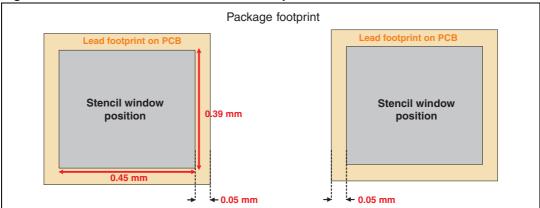
Stencil thickness (T) = 75 \sim 125 μm

Aspect Ratio =
$$\frac{W}{T} \ge 1.5$$

Aspect Area =
$$\frac{L \times W}{2T(L+W)} \ge 0.66$$

- 2. Reference design
 - a) Stencil opening thickness: 100 µm
 - b) Stencil opening for leads: Opening to footprint ratio between 60% and 65%.

Figure 16. Recommended stencil windows position



4.2 Solder paste

- 1. Halide-free flux qualification ROL0 according to ANSI/J-STD-004.
- 2. "No clean" solder paste is recommended.
- 3. Offers a high tack force to resist component movement during high speed
- 4. Solder paste with fine particles: powder particle size is 20-45 μm.

4.3 **Placement**

- 1. Manual positioning is not recommended.
- 2. It is recommended to use the lead recognition capabilities of the placement system, not the outline centering
- Standard tolerance of + 0.05 mm is recommended. 3.
- 3.5 N placement force is recommended. Too much placement force can lead to squeezed out solder paste and cause solder joints to short. Too low placement force can lead to insufficient contact between package and solder paste that could cause open solder joints or badly centered packages.
- To improve the package placement accuracy, a bottom side optical control should be 5. performed with a high resolution tool.
- For assembly, a perfect supporting of the PCB (all the more on flexible PCB) is recommended during solder paste printing, pick and place and reflow soldering by using optimized tools.

4.4 PCB design preference

- To control the solder paste amount, the closed via is recommended instead of open
- 2. The position of tracks and open vias in the solder area should be well balanced. The symmetrical layout is recommended, in case any tilt phenomena caused by asymmetrical solder paste amount due to the solder flow away.

4.5 Reflow profile

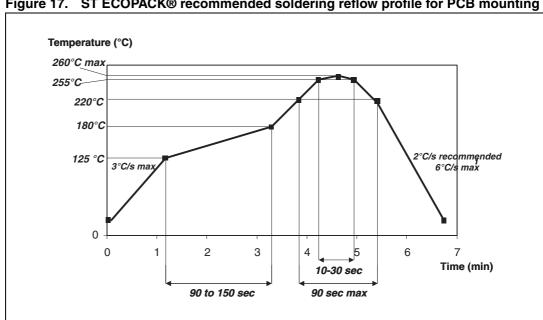


Figure 17. ST ECOPACK® recommended soldering reflow profile for PCB mounting

Note: Minimize air convection currents in the reflow oven to avoid component movement.

5 Ordering information

Table 4. Ordering information

Order code	Marking	Package	Weight	Base qty	Delivery mode
ESDALC6V1-1M2	N ⁽¹⁾	SOD882	0.92 mg	3000	Tape and reel

^{1.} The marking can be rotated by 90° to differentiate assembly location

6 Revision history

Table 5. Document revision history

Date Revision		Changes		
23-May-2006	1	Initial release		
16-Jun-2006	2	Updated tape and reel illustration (Figure 13).		
11-Oct-2006	3	Corrected formatting errors on page 1. No technical changes.		
10-May-2007	4	Updated Functional diagram to single diode. Added Section 4: Recommendation on PCB assembly.		
26-Nov-2007	5	Corrected 2: Ordering information scheme. Updated Figure 14: Tape and reel specifications. Added Figure 16: Recommended stencil windows position. Reformatted to current standards.		

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